The ePIC Barrel Imaging Calorimeter

System Testing Summary

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What do we test and why?

GlueX Baby BCal



cosmics

Baby BCAL

CODA based JLab readout

HGCROC based readout

Existing:

- Baby BCAL: ~60 cm long, 15.5 X₀ deep GlueX BCAL prototype with 40 SiPMs on each side (S12 Hamamatsu)
- CODA Based Readout: 250MHz fADCs, to TDC currently

To be upgraded:

- HGCROC Based readout
- New SiPM Board with BIC SiPMs (S14 Hamamatsu) and optical cookies

Goals:

- Test performance of Baby BCAL (response to muons) with new SiPMs, optical coupling (cookies) and HGCROC readout
- Benchmark against performance with previous readout (CODA based)
- Benchmark improvement in performance thanks to the new SiPMs

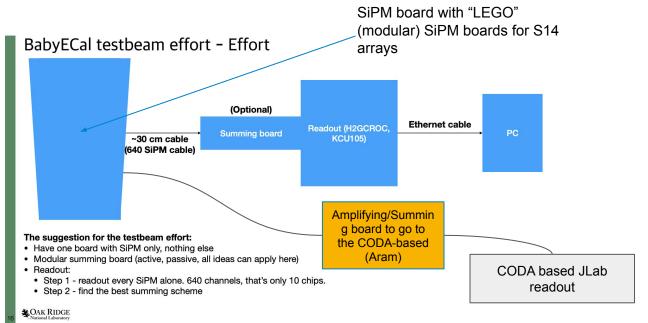


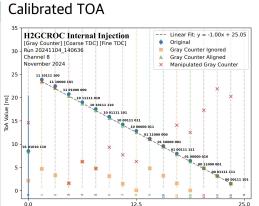
Beam Test Opportunity:

EM (e/ γ) beam with range of energies up to > 10 GeV (ideally)

Goal: linearity of response







Time (machine gun ignored) [ns]

16 SiPM

1000 | EEEMCal Prototype | Phase Scan | Channel 159, 1*GeV Electron | February 2025 | 10² | 10²

ToA Calibration:

- Crucial for BIC (SiFi/Pb) position resolution.
- EEEMC results suggest phase elimination is possible. PED tests should include ToA calibration efforts. Need direct tests for BIC.

Summing Scheme:

- Impacts signal shape and size.
- EEMCAL example shows risk of long signals—must investigate carefully.

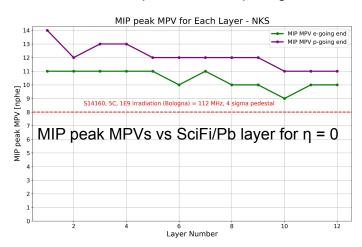


Simulation Feedback:

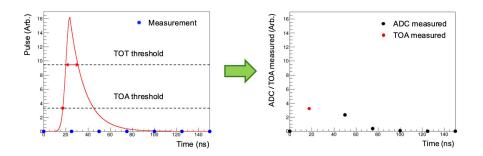
- Measurements must inform Minho's simulation.
- Align with PDR timeline—HGCROC parameters
 Pileup Studies:
- Estimate pileup from:
 - Two physics events.
 - Background + signal.
- Revisit Jeff's background numbers.

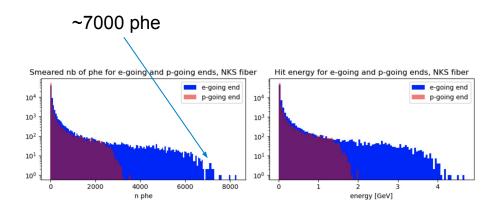
Photon Statistics:

Mean number of photoelectrons per signal



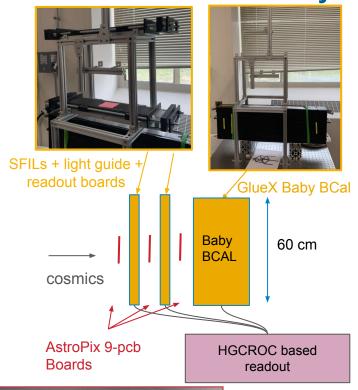
ADC, TOA, and TOT measurements







What do we test and why?



To be upgraded:

- 2 SFILs (Scintillating Fiber/Pb Intermediate (thin) Layers) with S14 SiPMs (existing, but to be compatible with the HGCROC readout)
- 9-chip pcb boards (eventually 3 of them, starting from one)

Goals:

- Show the performance of the Integrated System of AstroPix 9-chip (daisy-chained chips) with SciFi: synchronization is needed
 - Read 3 9-chip PCB boards in sync
 - Read 9-chip PCB board and SciFi (HGCROC) in sync
 - The sync work can start with quad/single chip
- Develop basis for the cross-calibration procedure (position and energy)
- Additionally: Develop basis for the large scale AstroPix energy calibration with sources (AstroPix v4 single chip based)

Beam Test Opportunity:

- EM (e/ɣ) beam with range of energies up to > 10 GeV (ideally), Goal: linearity of response
- e/π beam with range of energies up to > 10 GeV (ideally), **Goal:** e/π separation

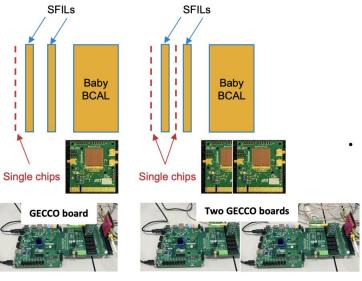


System Testing Plan

Plan for Synchronization

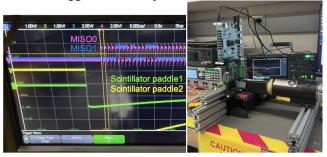
Possible setup of system integration at bench test in ANL:

U.S. DEPARTMENT OF ENERGY U.S. Department of Energy laboratory managed by UChicago Argonne, LLC.



How to synchronize?

- Plan A
 - ## LVDS MISO0/1 signals that generated from Astropix used as trigger IN for baby bcal



- Plan B
 - Provide up to 10 MHz LVDS external clock to Astropix chip via PMOD







Sync of AstroPix with HGCROC (Proof of principle)

Sync ASTROPIX with external clock (Bobae)

Norbert will test sync of HGCROC with external clock using small scintillator

- In the next step we will combine two together and test the AstroPix HGCROC sync (visit ORNL in May?)
- We might also be able to read AstroPix with the FPGA that reads the HGCROC board
- Workforce and PED planning
 - Workforce needed for investigating the readout parameters with HGCROC to find the optimal summing configuration, to stay on track with the PED timeline
 - Tests will be also happening in Korea

Discussion about the QC (chip/module/tray) tests, system tests and calibration

Calibration of the sensors needed at scale

- V4 will help clarify calibration procedures, but the ultimate tests and procedure development will be possible with the new v5 chip
- Verify needs for temperature dependent relative calibration

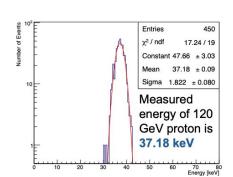
Initial thoughts:

Calibration Steps

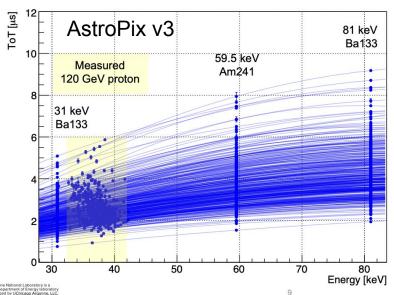
- Threshold tuning at module/chip QC level
- Absolute calibration with source at system level
- PCB thickness on modules may complicate source-based calibration(?) (verify)

From the System Testing/Module-Wafer discussion is clear that **we need to rerun the simulation on the physics performance** (energy splitting and resolution from AstroPix) with non fully depleted chip: smaller dynami range (let's check 250 keV)

Common meeting on Modules/Wafers/System QC in 2 weeks







Calibration



Overall System Calibration

- How material non-uniformity impacts the EM shower calibration performance?
 - Simulate sampling fraction vs energy for each SFIL (layer dependent), reviewers ask about the calibration procedure
 - Include both MIPs (muons) and electrons
 - We can also extract it from the beam test results from the KEK
- AstroPix energy calibration separate (energy calibration absolute from sources, relative later in-situ)
- Alignment calibration mostly from muons, with initial metrology (to be tested with first modules)
- Cross calibration of systems possible and to be tested in PREP in full system: we expect it will introduce improvements on top of the single-system calibration: e.g. position calibration for SciFi/Pb cross calibrated with AstroPix position

